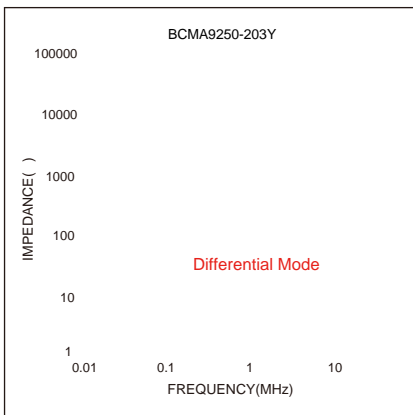
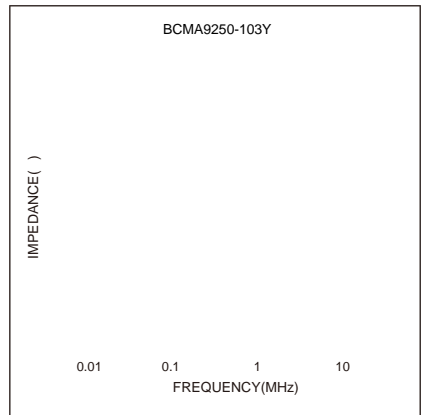
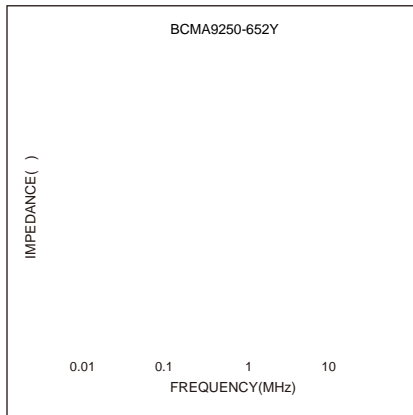
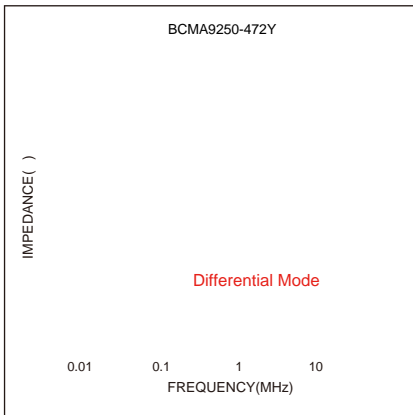
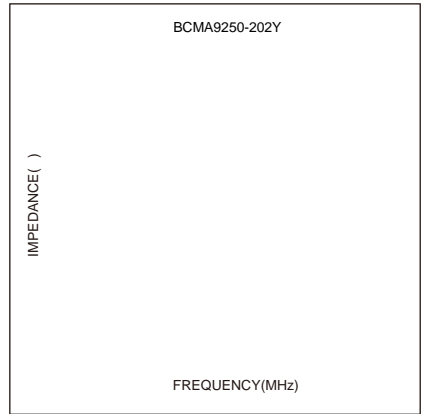
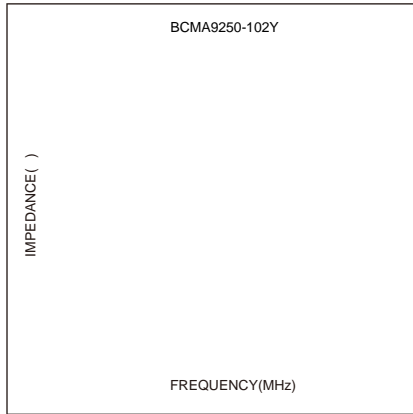
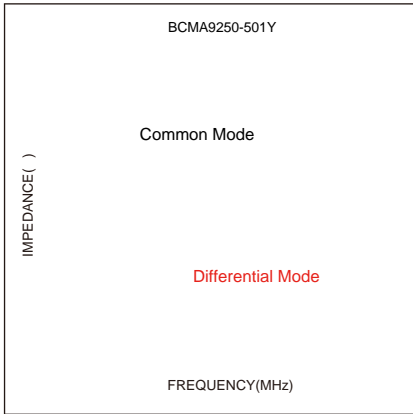
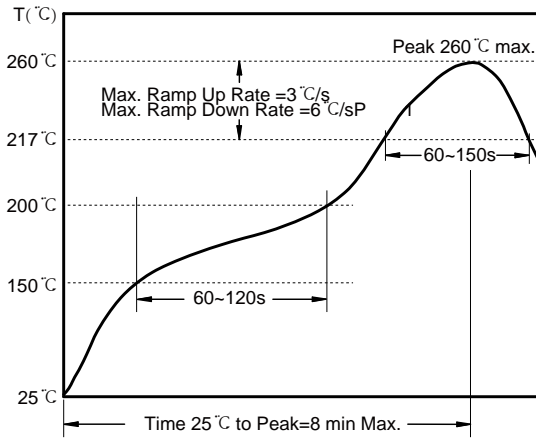

Part No



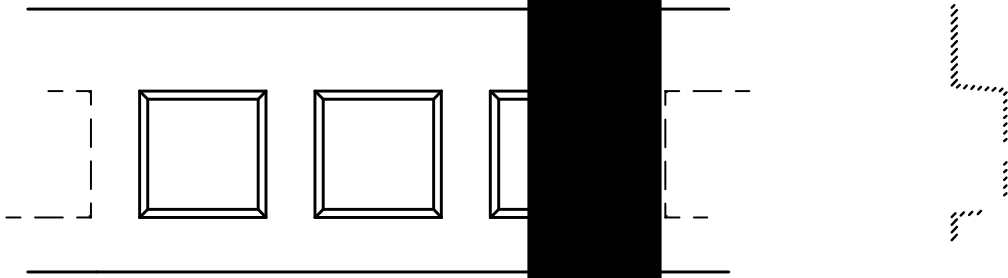
Soldering Reflow:



Preheat condition: 150 ~200 °C/ 60~120 sec.
 Allowed time above 217 °C: 60~150 sec.
 Max temperature: 260 °C.
 Allowed Reflow time: 2x max.

Packaging Information:

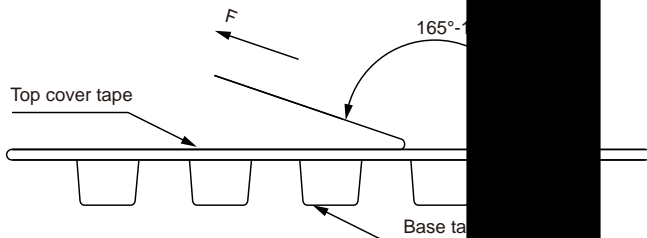
Tape Dimension :



Series	A0 (mm)	B0 (mm)	D (mm)
BCMA9250	6.5 typ	9.7 typ	1.5±0.1

P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
12.0±0.1	16.0±0.3	5.7 ref.	1.75±0.1	0.4±0.1

Peel force of top cover tape:

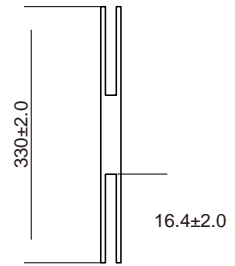
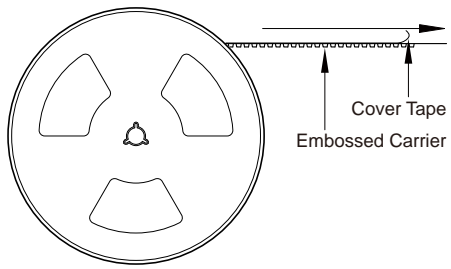


The peel force of top cover tape shall be 0.1 to 1.3 N

Product Marking:

Marking	Dot+Printing (Duplex)	Printing (Split winding)

Reel Dimension: [mm]



Packaging Quantity: